



Receipt

#7

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

ABE ET AL

Application No.: 09/726,588

Group Art Unit: 1725

Filed: December 1, 2000

For: THERMOSETTING SOLDERING FLUX AND SOLDERING PROCESS

SECOND REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

An error has been noted on the Official Filing Receipt in the referenced application. Namely, the indicated filing date is incorrect. The correct filing date is December 1, 2000. Please issue a Corrected Official Filing Receipt correcting this error as marked in red on the attached copy of the Official Filing Receipt. A request for correction of the filing receipt was submitted on May 20, 2001, but a corrected version of the Official Filing Receipt has still not been received.

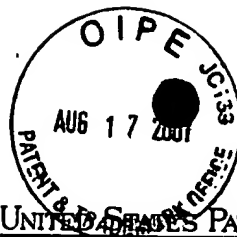
Respectfully submitted,

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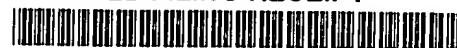
COMMISSIONER FOR PATENTS
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO.	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/726,588	04/13/2001	1725	970			16	2

27649
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↑ Correct date
is 12/01/2000

CONFIRMATION NO. 4417
UPDATED FILING RECEIPT



OC000000006048406

Date Mailed: 05/07/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

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Domestic Priority data as claimed by applicant**Foreign Applications**

JAPAN 344979/1999 12/03/1999

If Required, Foreign Filing License Granted 02/07/2001

Projected Publication Date: 08/16/2001

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Early Publication Request: No

Title

Thermosetting soldering flux and soldering process

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Preliminary Class

228

Data entry by : GIZAW, ASTER

Team : OIPE

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